

/ Absolute Maximum Ratings(Ta=25)

Parameter	Symbol	Rating	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RM} V_{RSM} V_{DC}	100	V
RMS Reverse Voltage	V_{RMS}	70	V
Average forward rectified current	$I_{F(AV)}$	1×10	A
Non Repetitive Peak Surge Current	I_{FSM}	200	A
Typical Thermal Resistance ^{Note 1}	R_{JA}	70	/W
	R_{Jc}	1.4	/W
Junction and Storage Temperature Range	T_j T_{stg}	-55 +150	

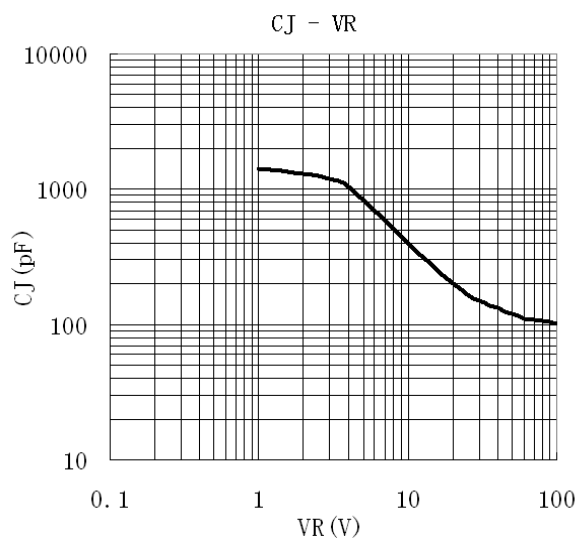
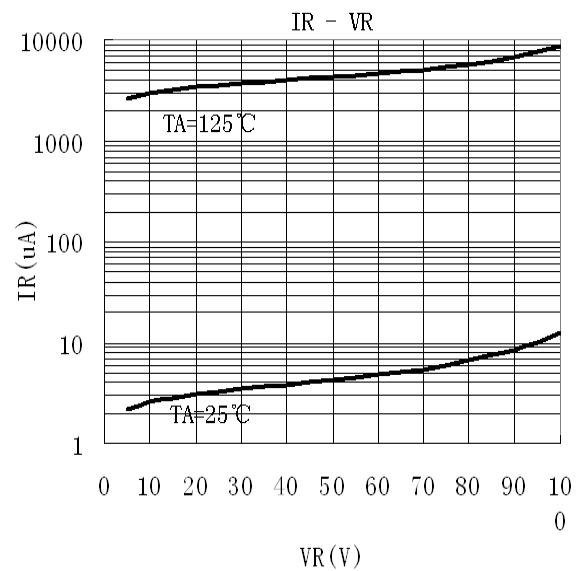
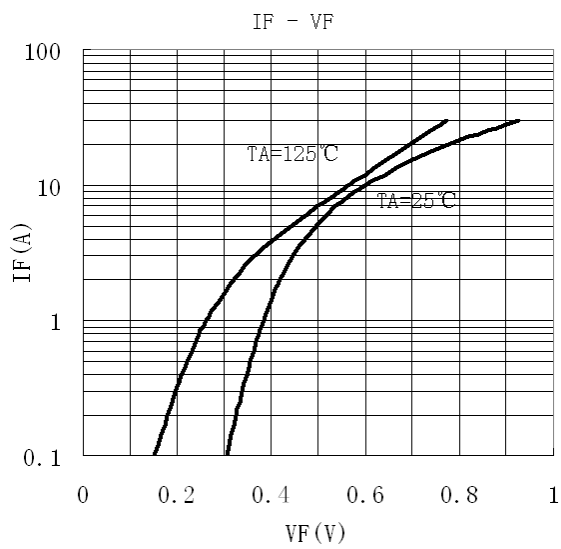
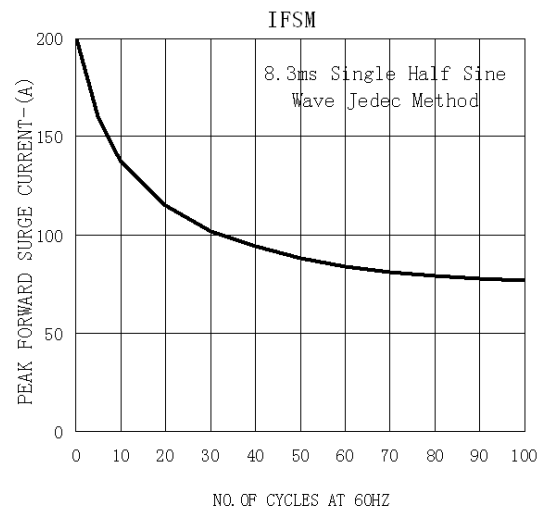
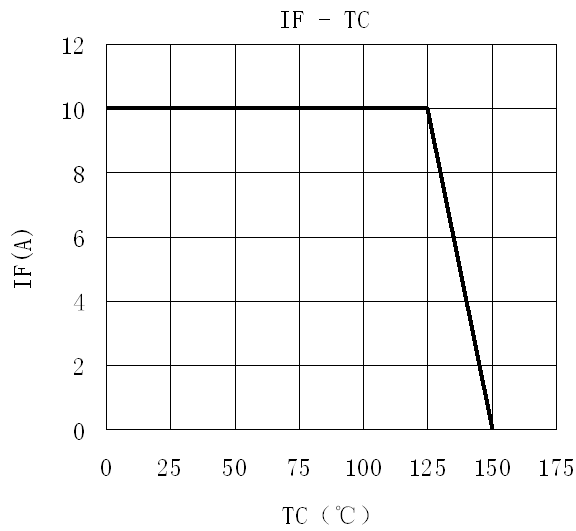
/ Electrical Characteristics(Ta=25)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Reverse Voltage	$V_{(BR)R}$	$I_R=1mA(Ta=25)$	100			V
Forward Voltage	V_F	$I_F=2A(Ta=25)$		0.41	0.45	V
		$I_F=10A(Ta=25)$		0.58	0.65	V
		$I_F=2A(Ta=125)$		0.31	0.40	V
		$I_F=10A(Ta=125)$		0.55	0.65	V
Instantaneous Reverse Current	I_R ^{Note 2}	$V_R=100V(Ta=25)$			150	A
		$V_R=100V(Ta=125)$			25	mA

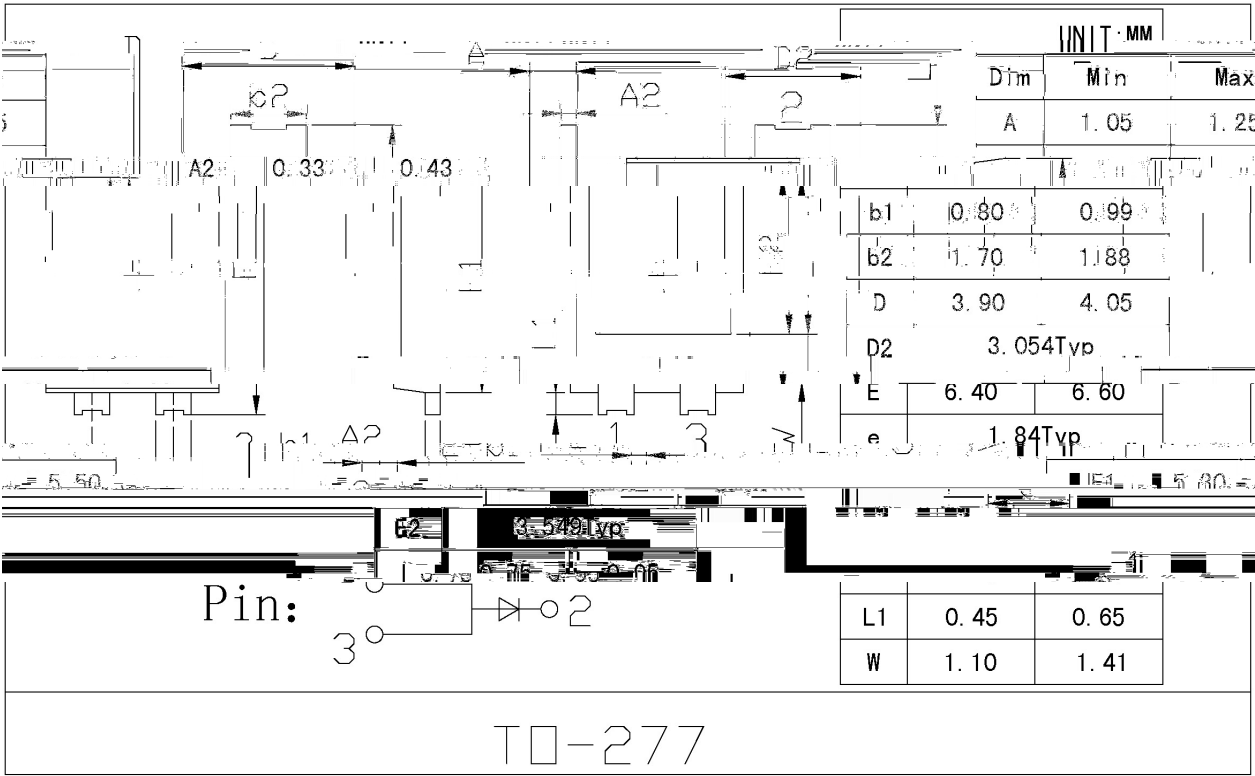
/Notes

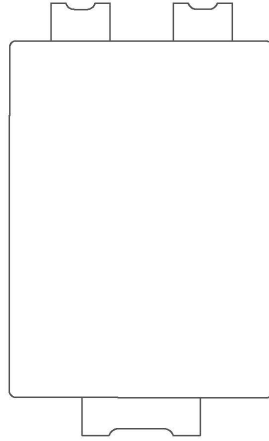
1. PCB 2 18.8mm x 14.4mm 5.6mm x 14.4mm
Polymide PCB, 2oz. Copper. Cathode pad dimensions 18.8mm x 14.4mm. Anode pad dimensions 5.6mm x 14.4mm.
2.
Short duration pulse test used to minimize self-heating effect.
3.
Unless otherwise noted, values for the parameters of a single chip.

/ Electrical Characteristic Curve



/ Package Dimensions





() / Temperature Profile for IR Reflow Soldering(Pb-Free)

- Note:

1

150 180

60 90sec;

1.Preheating:150~180 , Time:60~90sec.

2

245±5

5±0.5sec;

2.Peak Temp.:245±5 , Duration:5±0.5sec.

3

2 10 /sec.

3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

260±5 10±1 sec. Temp.:260±5 Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type	Units/Reel /	Reels/Inner Box /  	Units	Dimension (unit mm ³)
--------------	-----------------	--	-------	--------------------------------------